CEL

Solid State Relay
OCMOS FET

PS7241-1C

8-PIN SOP 400 V BREAK DOWN VOLTAGE TRANSFER TYPE 2-ch Optical Coupled MOS FET

DESCRIPTION

The PS7241-1C is a transfer type solid state relay containing normally open (N.O.) contact and normally close (N.C.) contact on output side.

It is suitable for analog signal control because of their low offset and high linearity.

FEATURES

- 2 channel type (1 a + 1 b output)
- Low LED operating current (I_F = 2 mA)
- Designed for AC/DC switching line changer
- Small and thin package (8-pin SOP, Height = 2.1 mm)
- Low offset voltage
- Ordering number of taping product: PS7241-1C-F3, F4
- UL approved: File No. E72422 (S)
- BSI approved: No. 8241/8242
- CSA approved: No. CA 101391
- VDE approved: No. 121302 ÜG

APPLICATIONS

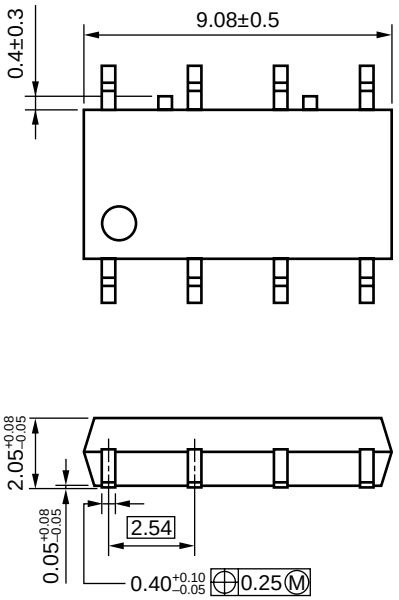
- Exchange equipment
- Measurement equipment
- FA/OA equipment

Document No. PN10303EJ01V1DS (1st edition)
(Previous No. P13266EJ4V0DS00)
Date Published February 2003 CP(K)

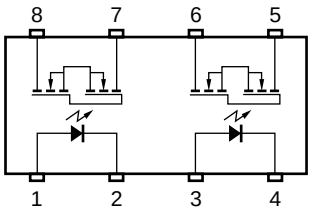
The mark ★ shows major revised points.

PACKAGE DIMENSIONS

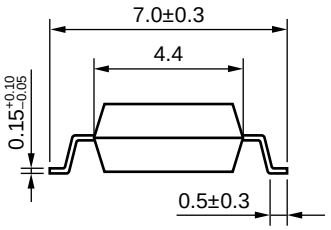
(in millimeters)



TOP VIEW



1. LED Anode
2. LED Cathode
3. LED Anode
4. LED Cathode
5. MOS FET (N.O.)
6. MOS FET (N.O.)
7. MOS FET (N.C.)
8. MOS FET (N.C.)



ORDERING INFORMATION (Solder Contains Lead)

Part Number	Package	Packing Style	Application Part Number*1
PS7241-1C	8-pin SOP	Magazine case 45 pcs	PS7241-1C
PS7241-1C-F3		Embossed Tape 1 500 pcs/reel	
PS7241-1C-F4			

***1** For the application of the Safety Standard, following part number should be used.

ORDERING INFORMATION (Pb-Free)

Part Number	Package	Packing Style	Application Part Number*1
PS7241-1C-A	8-pin SOP	Magazine case 45 pcs	PS7241-1C
PS7241-1C-F3-A		Embossed Tape 1 500 pcs/reel	
PS7241-1C-F4-A			

***1** For the application of the Safety Standard, following part number should be used.

ABSOLUTE MAXIMUM RATINGS (T_A = 25 °C, unless otherwise specified)

Parameter		Symbol	Ratings	Unit
Diode	Forward Current (DC)	I_F	50	mA
	Reverse Voltage	V_R	5	V
	Power Dissipation	P_D	50	mW/ch
	Peak Forward Current*1	I_{FP}	1	A
MOS FET	Break Down Voltage	V_L	400	V
	Continuous Load Current	I_L	120	mA
	Pulse Load Current*2 (AC/DC Connection)	I_{LP}	200	mA
	Power Dissipation	P_D	180	mW/ch
Isolation Voltage*3		BV	1 500	Vr.m.s.
Total Power Dissipation		P_T	460	mW
★ Operating Ambient Temperature		T_A	–40 to +85	°C
Storage Temperature		T_{stg}	–40 to +100	°C

***1** PW = 100 μs, Duty Cycle = 1 %

***2** PW = 100 ms, 1 shot

***3** AC voltage for 1 minute at T_A = 25 °C, RH = 60 % between input and output

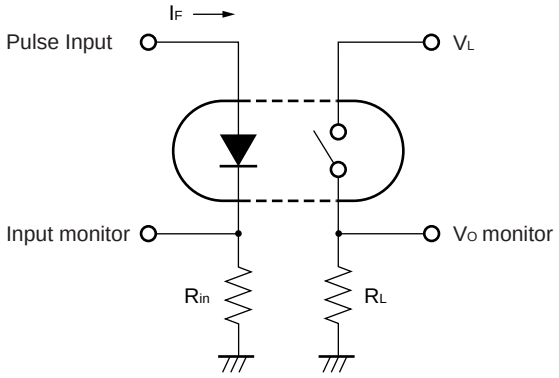
RECOMMENDED OPERATING CONDITIONS (T_A = 25 °C)

Parameter	Symbol	MIN.	TYP.	MAX.	Unit
LED Operating Current	I_F	2	10	20	mA
LED Off Voltage	V_F	0		0.5	V

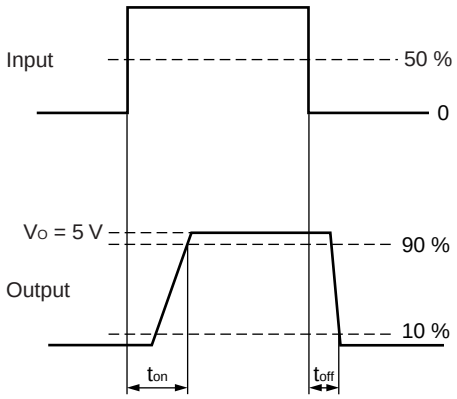
ELECTRICAL CHARACTERISTICS (T_A = 25 °C)

Parameter		Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Diode	Forward Voltage	V_F	I_F = 10 mA		1.2	1.4	V
	Reverse Current	I_R	V_R = 5 V			5	μA
MOS FET	Off-state Leakage Current	I_{Loff}	N.O.: I_F = 0 mA, V_D = 400 V		0.03	1.0	μA
			N.C.: I_F = 10 mA, V_D = 400 V				
	Output Capacitance	C_{out}	N.O.: V_D = 0 V, f = 1.0 MHz		65		pF/ch
			N.C.: V_D = 0 V, f = 1.0 MHz, I_F = 10 mA		185		
Coupled	LED On-state Current	I_{Fon}	N.O.: I_L = 120 mA			2.0	mA
	LED Off-state Current	I_{Foff}	N.C.: I_L = 120 mA				
	On-state Resistance	R_{on1}	N.O.: I_F = 10 mA, I_L = 10 mA		21	30	Ω
			N.C.: I_F = 0 mA, I_L = 10 mA				
		R_{on2}	N.O.: I_F = 10 mA, I_L = 120 mA, t ≤ 10 ms		16	25	
			N.C.: I_F = 0 mA, I_L = 120 mA, t ≤ 10 ms				
★	Turn-on Time *1	$t_{on\ (N.O.)}$	I_F = 10 mA, V_O = 5 V, R_L = 2 kΩ,		0.2	1.0	ms
		$t_{on\ (N.C.)}$	PW ≥ 10 ms		0.02	0.2	
	Turn-off Time *1	$t_{off\ (N.O.)}$			0.02	0.2	
		$t_{off\ (N.C.)}$			0.1	1.0	
	Isolation Resistance	R_{I-O}	V_{I-O} = 1.0 kV_{DC}	10^9			Ω
	Isolation Capacitance	C_{I-O}	V = 0 V, f = 1.0 MHz		0.4		pF/ch

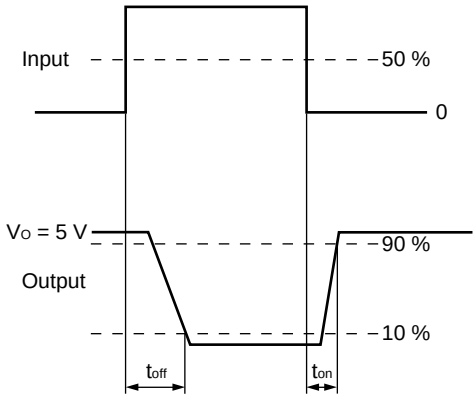
***1** Test Circuit for Switching Time



N.O. (between pin 5 and 6)

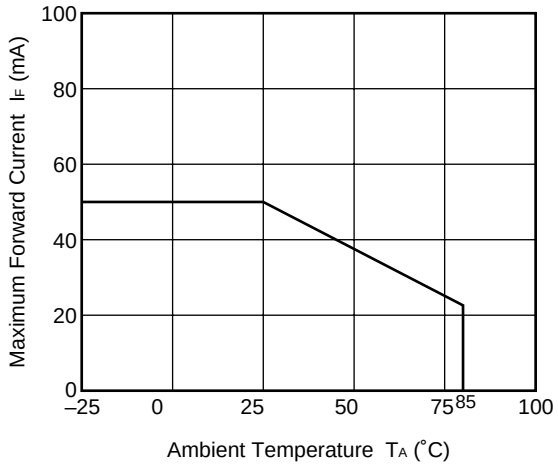


N.C. (between pin 7 and 8)

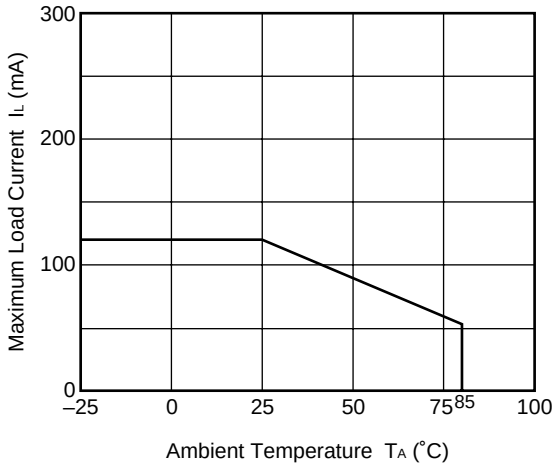


★ **TYPICAL CHARACTERISTICS (T_A = 25 °C, unless otherwise specified)**

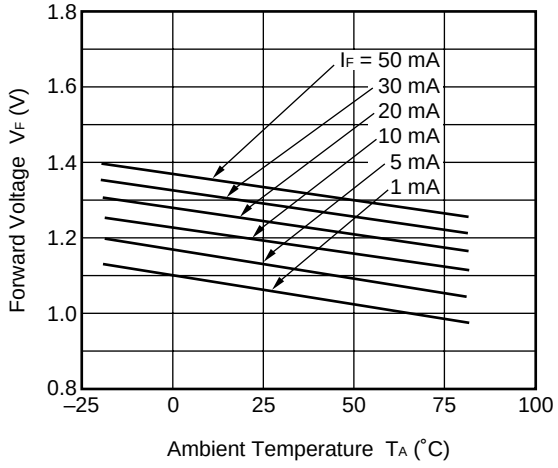
MAXIMUM FORWARD CURRENT vs. AMBIENT TEMPERATURE



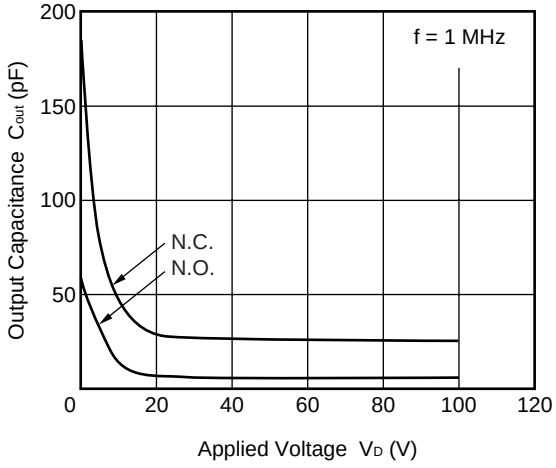
MAXIMUM LOAD CURRENT vs. AMBIENT TEMPERATURE



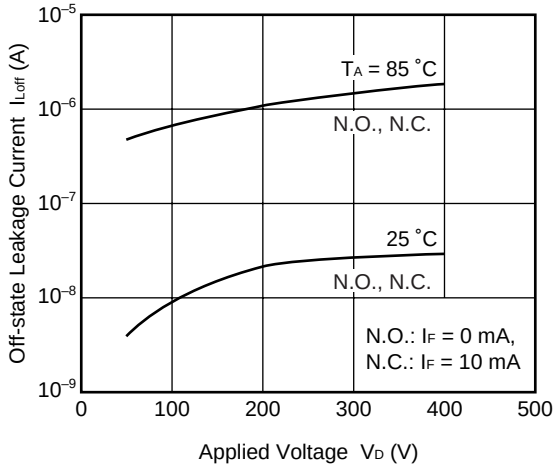
FORWARD VOLTAGE vs. AMBIENT TEMPERATURE



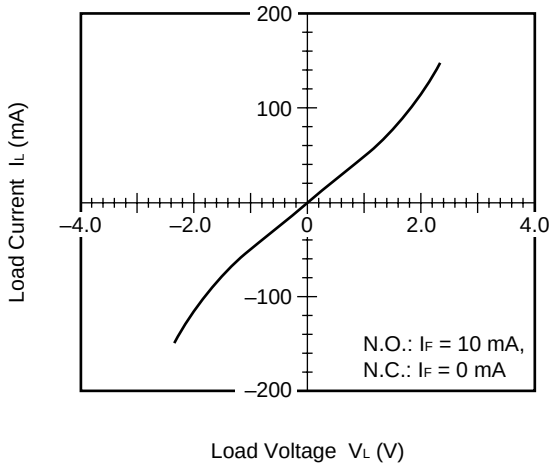
OUTPUT CAPACITANCE vs. APPLIED VOLTAGE



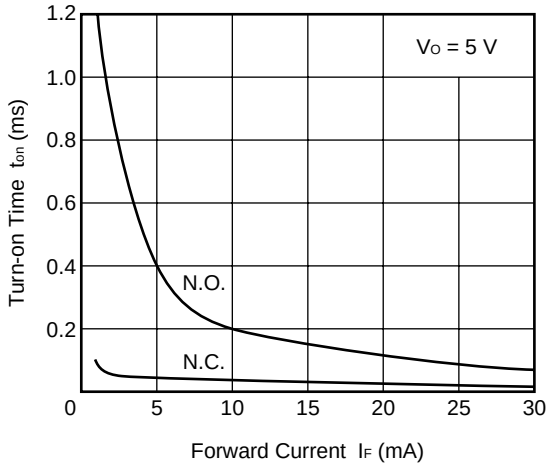
OFF-STATE LEAKAGE CURRENT vs. APPLIED VOLTAGE



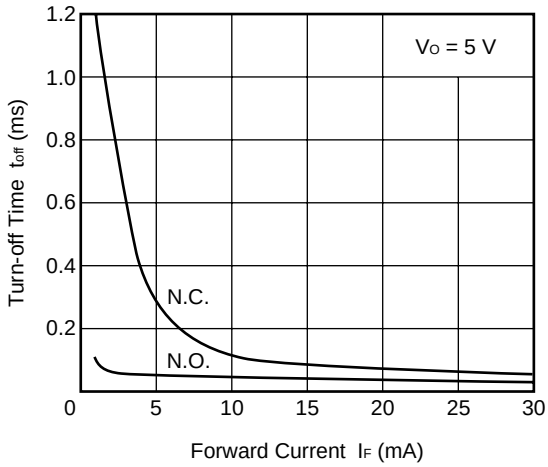
LOAD CURRENT vs. LOAD VOLTAGE



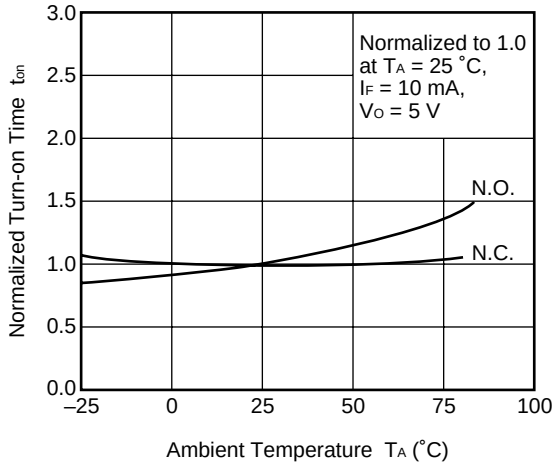
TURN-ON TIME vs. FORWARD CURRENT



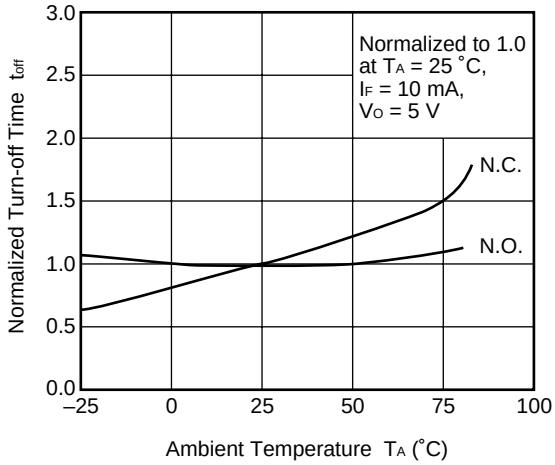
TURN-OFF TIME vs. FORWARD CURRENT



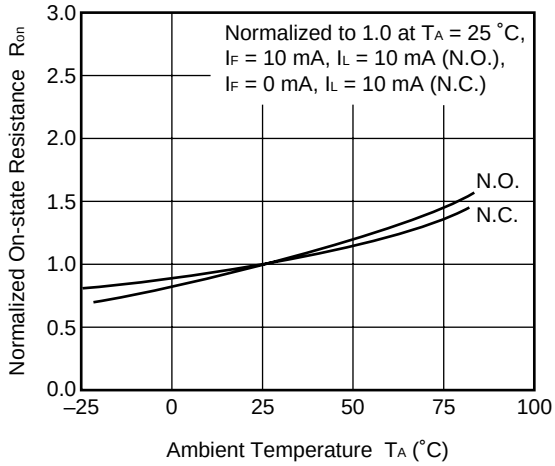
NORMALIZED TURN-ON TIME vs. AMBIENT TEMPERATURE



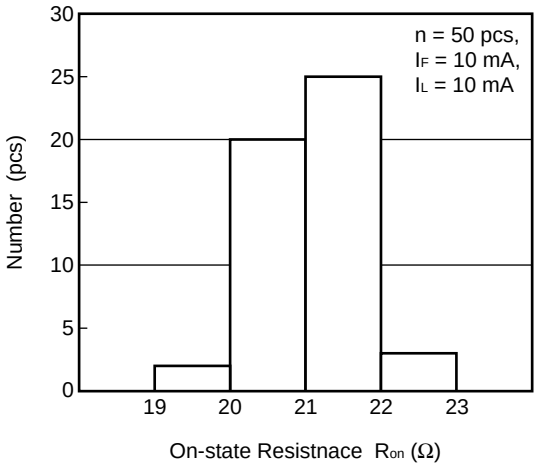
NORMALIZED TURN-OFF TIME vs. AMBIENT TEMPERATURE



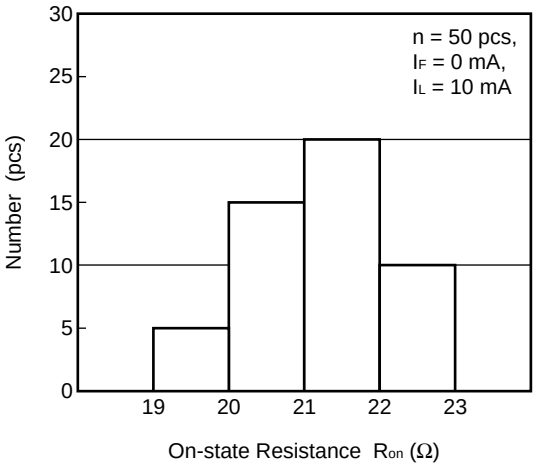
NORMALIZED ON-STATE RESISTANCE vs. AMBIENT TEMPERATURE



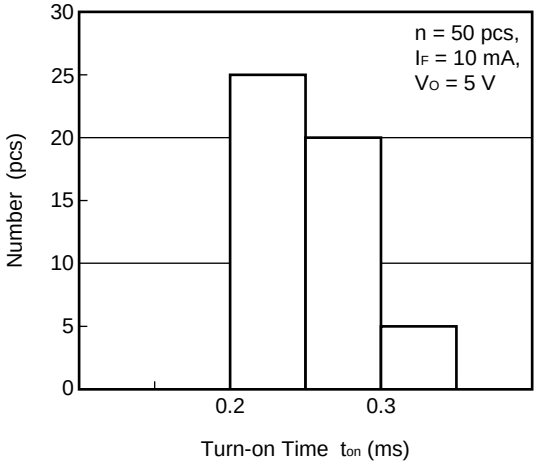
ON-STATE RESISTANCE (N.O.) DISTRIBUTION



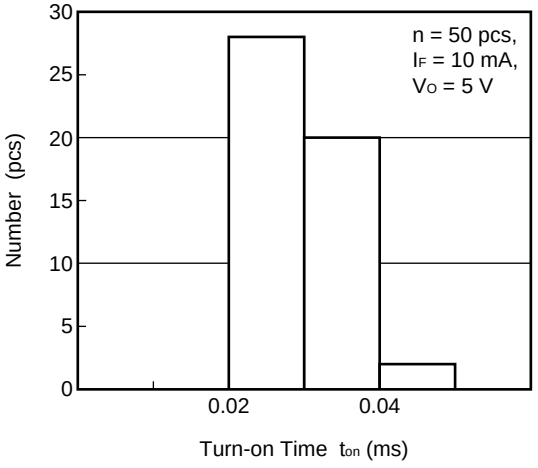
ON-STATE RESISTANCE (N.C.) DISTRIBUTION



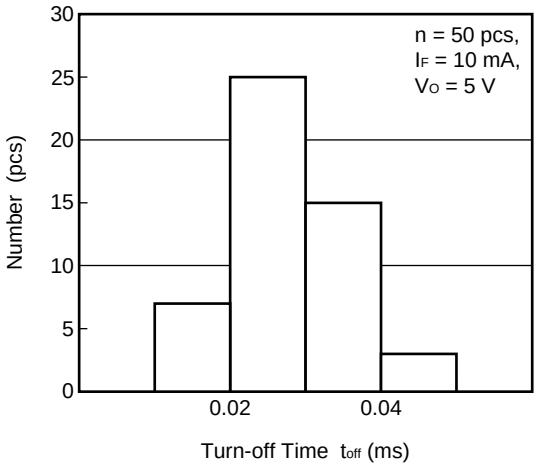
TURN-ON TIME (N.O.) DISTRIBUTION



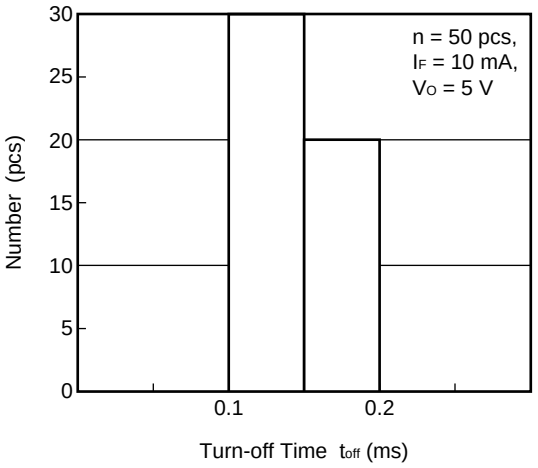
TURN-ON TIME (N.C.) DISTRIBUTION



TURN-OFF TIME (N.O.) DISTRIBUTION



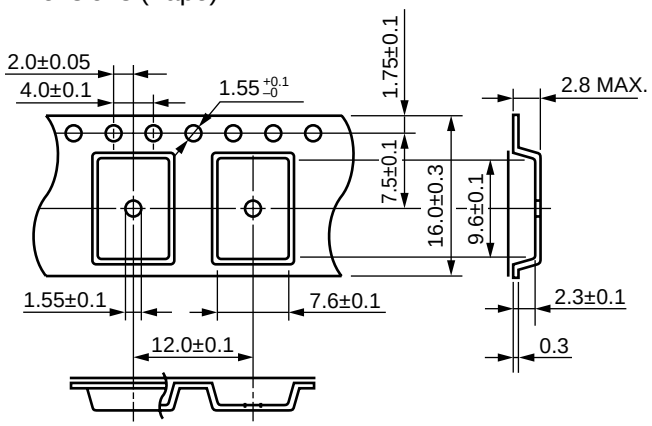
TURN-OFF TIME (N.C.) DISTRIBUTION



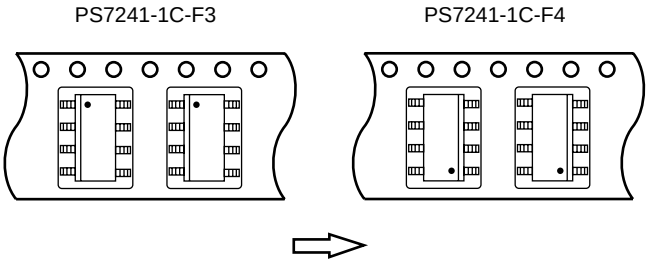
Remark The graphs indicate nominal characteristics.

★ **TAPING SPECIFICATIONS (in millimeters)**

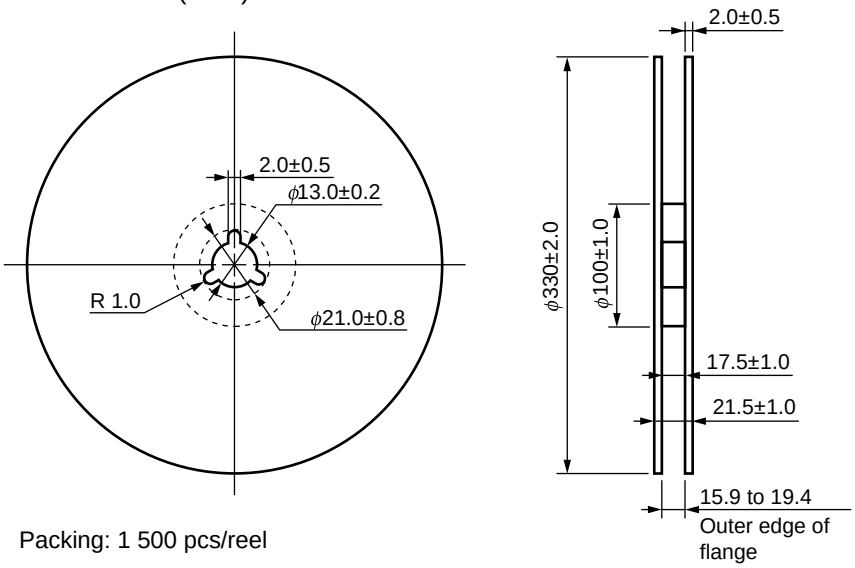
Outline and Dimensions (Tape)



Tape Direction



Outline and Dimensions (Reel)



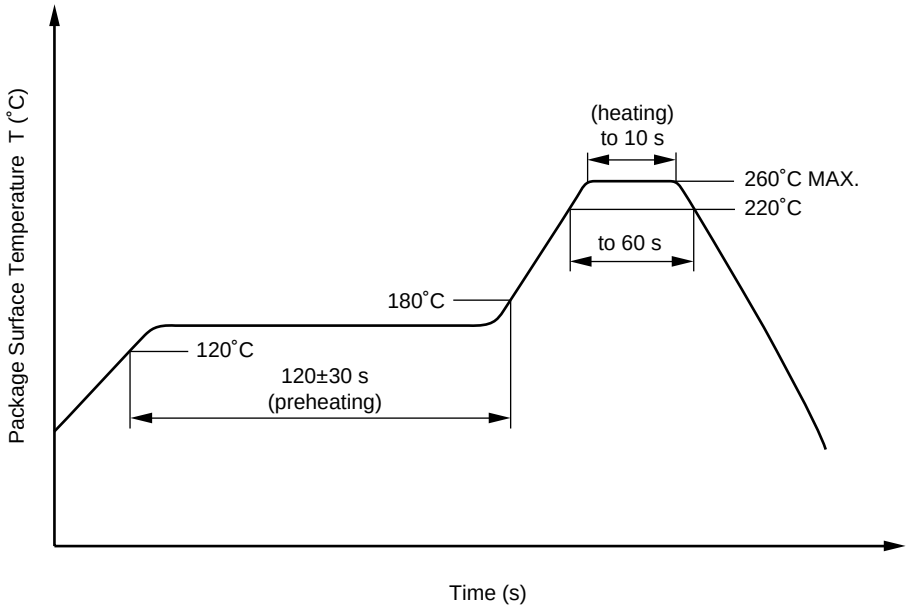
Packing: 1 500 pcs/reel

★ RECOMMENDED SOLDERING CONDITIONS

(1) Infrared reflow soldering

• Peak reflow temperature	260°C or below (package surface temperature)
• Time of peak reflow temperature	10 seconds or less
• Time of temperature higher than 220°C	60 seconds or less
• Time to preheat temperature from 120 to 180°C	120±30 s
• Number of reflows	Three
• Flux	Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

Recommended Temperature Profile of Infrared Reflow



(2) Wave soldering

• Temperature	260°C or below (molten solder temperature)
• Time	10 seconds or less
• Preheating conditions	120°C or below (package surface temperature)
• Number of times	One
• Flux	Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

(3) Cautions

• Fluxes

Avoid removing the residual flux with freon-based and chlorine-based cleaning solvent.

CEL California Eastern Laboratories

4590 Patrick Henry Drive
Santa Clara, CA 95054-1817
Telephone: (408) 919-2500
Facsimile: (408) 988-0279

Subject: Compliance with EU Directives

CEL certifies, to its knowledge, that semiconductor and laser products detailed below are compliant with the requirements of European Union (EU) Directive 2002/95/EC Restriction on Use of Hazardous Substances in electrical and electronic equipment (RoHS) and the requirements of EU Directive 2003/11/EC Restriction on Penta and Octa BDE.

CEL Pb-free products have the same base part number with a suffix added. The suffix –A indicates that the device is Pb-free. The –AZ suffix is used to designate devices containing Pb which are exempted from the requirement of RoHS directive (*). In all cases the devices have Pb-free terminals. All devices with these suffixes meet the requirements of the RoHS directive.

This status is based on CEL's understanding of the EU Directives and knowledge of the materials that go into its products as of the date of disclosure of this information.

Restricted Substance per RoHS	Concentration Limit per RoHS (values are not yet fixed)	Concentration contained in CEL devices	
Lead (Pb)	< 1000 PPM	-A	-AZ
		Not Detected	(*)
Mercury	< 1000 PPM	Not Detected	
Cadmium	< 100 PPM	Not Detected	
Hexavalent Chromium	< 1000 PPM	Not Detected	
PBB	< 1000 PPM	Not Detected	
PBDE	< 1000 PPM	Not Detected	

If you should have any additional questions regarding our devices and compliance to environmental standards, please do not hesitate to contact your local representative.